L Number	Hits	Search Text	DB	Time stamp
1	3467	etch\$3 same ((rectangular or rectangle or square) with (substrate\$1 or wafer\$1))	USPAT; US-PGPUB:	2002/09/25 16:57
			EPO; JPO;	
		,	DERWENT;	
15	366	(etch\$3 same ((rectangular or rectangle or square) with (substrate\$1 or wafer\$1))) and ((uniformity or uniform) with etch\$3)	IBM_TDB USPAT:	2002/00/05 40-50
			US-PGPUB;	2002/09/25 16:58
			EPO; JPO;	
			DERWENT;	
22	70	//otah@aama //aata	IBM_TDB	
22	70	((etch\$3 same ((rectangular or rectangle or square) with (substrate\$1 or wafer\$1))) and ((uniformity or uniform) with etch\$3)) and ((second adj4 power) or (second adj4 electrode))	USPAT;	2002/09/25 17:00
			US-PGPUB;	
			EPO; JPO;	
i I			DERWENT;	
			IBM_TDB	